

Repair Stick Multi Purpose



Fast-curing, mineral-filled, drinking water approval
Temperature resistance: -25°C (-13°F) to +120°C (+248°F)

The all-round product for quick, permanent, elastic and non-shrinking repairs and touch-ups on nearly all surfaces. Repair Stick Multi fills and seals cracks, holes, damages and leaks. It can be used on metal, wood, stone, glass, plastic and many other materials.

Thanks to its versatile use, WEICON Repair Stick Multi can be used in various industrial fields as well as in trades and the DIY sector.



Technical Data

Basis	epoxy resin mineral-filled
Texture	pasty
Colour after curing	white
Mixing ratio by weight (resin/hardener)	1:1
Density of the mixture	1.9 g/cm ³
Gap bridging up to max.	15 mm
Processing temperature	+10 bis +40°C
Curing temperature	+6 bis +40°C
Pot life for 25g preparation and +20°C (+68°F)	4 min.
Handling strength (35% strength) after	15 min.
Capable of bearing mechanical loads (50% strength) after	60 min.
Final strength (100% strength) after	24 h
Pressure	40 N/mm ²
Medium tensile shear strength after 7 days at +20°C (+68°F) acc. to DIN 532832 on	steel, sandblasted: 6.5N/mm ²
Shore hardness D	70

Note

The specifications and recommendations given in this technical data sheet must not be seen as guaranteed product characteristics. They are based on our laboratory tests and on practical experience. Since individual application conditions are beyond our knowledge, control and responsibility, this information is provided without any obligation. We do guarantee the continuously high quality of our products. However, own adequate laboratory and practical tests to find out if the product in question meets the requested properties are recommended. A claim cannot be derived from them. The user bears the only responsibility for non-appropriate or other than specified applications.

Thermal conductivity (ASTM D 257)	0.40 W/m.K
Dielectric strength (ASTM D 149)	3.0 kV/mm
Thermal expansion coefficient (ISO 11359)	30-40 x 10 ⁻⁶ K ⁻¹
Temperature resistance	-25 to +120, short-term up to +150°C
Shrinkage	0.02 %

Surface pre-treatment

For a flawless adhesive bond, surfaces must be clean And dry (e.g. clean and degrease with WEICON Surface Cleaner).

Application

WEICON Repair Sticks can bridge a bonding gap of max. 15 mm per work step. The specified pot life refers to a material preparation of 25g at room temperature. Larger preparation quantities result in a faster curing time due to the typical reaction heat of epoxy resins (exothermic reaction). Higher temperatures also reduce the pot life and curing time. (General rule: every increase by +10°C above room temperature results in a decrease of the pot life and curing time by half). Temperatures below +16°C increase the pot life and curing time significantly. From approx. +5°C and below, no reaction takes place.

Storage

When unopened, WEICON Repair Sticks can be stored at a constant room temperature of approx. +20°C in a dry place for at least 18 months. Protect from direct sunlight.

Safety and health

When using WEICON products, the physical, safety technical, toxicological and ecological data and regulations in our EC safety data sheets (www.weicon.com) must be observed.

Available sizes:

10539057 Repair Stick Multi Purpose 28 g
 10539115 Repair Stick Multi Purpose 56 g